Silicon N-Channel MOS FET

HITACHI

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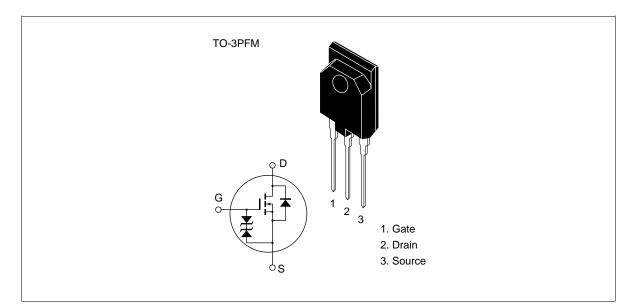
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switchingregulator, DC-DC converter

Outline





Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Ratings	Unit
Drain to source voltage	K1831	V _{DSS}	450	V
	K1832		500	
Gate to source voltage		V _{GSS}	±30	V
Drain current		I _D	10	А
Drain peak current		I *1 D(pulse)	30	А
Body to drain diode reverse dra	I _{DR}	10	А	
Channel dissipation	Pch* ²	50	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes 1. PW \leq 10 μ s, duty cycle \leq 1 %

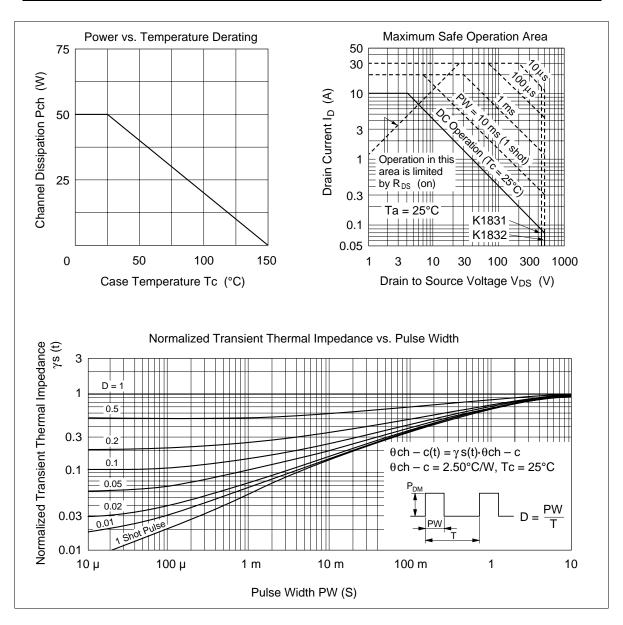
2. Value at Tc = 25 °C

Electrical Characteristics (Ta = 25°C)

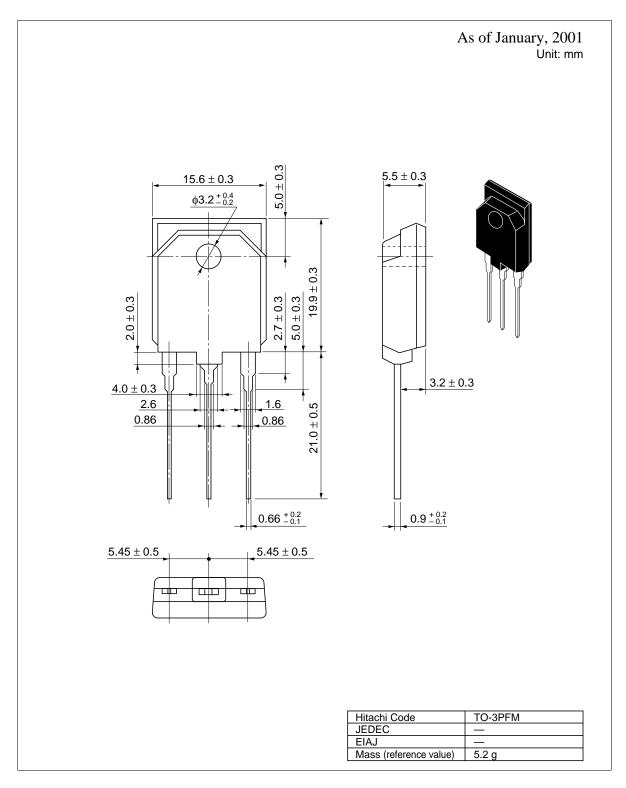
ltem		Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source	K1831	$V_{(BR)DSS}$	450	_	_	V	$I_{\rm D}$ = 10 mA, $V_{\rm GS}$ = 0
breakdown voltage	K1832		500	_	_		
Gate to source b voltage	reakdown	$V_{(\text{BR})\text{GSS}}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current		I _{GSS}		—	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, \text{ V}_{DS} = 0$
Zero gate	K1831	I _{DSS}		_	250	μA	$V_{\rm DS} = 360 \text{ V}, \text{ V}_{\rm GS} = 0$
voltage drain current	K1832						$V_{\rm DS} = 400 \ V, \ V_{\rm GS} = 0$
Gate to source c	utoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_{\rm D}$ = 1 mA, $V_{\rm DS}$ = 10 V
Static drain to	K1831	$R_{\text{DS(on)}}$	_	0.6	0.8	Ω	I _D = 5 A
source on state resistance	K1832		_	0.7	0.9		$V_{GS} = 10 V^{*1}$
Forward transfer	admittance	y _{fs}	4.0	7.0	_	S	$I_{\rm D} = 5 \text{ A}$ $V_{\rm DS} = 10 \text{ V}^{*1}$
Input capacitance		Ciss		1050	_	pF	V _{DS} = 10 V
Output capacitance		Coss		280	_	pF	$V_{GS} = 0$
Reverse transfer	capacitance	Crss	_	40	_	pF	f = 1 MHz
Turn-on delay tin	ne	t _{d(on)}		15	_	ns	I _D = 5 A
Rise time		t,		60	_	ns	V _{GS} = 10 V
Turn-off delay tin	ne	t _{d(off)}	—	90	_	ns	$R_{L} = 6 \Omega$
Fall time		t _f	—	45	—	ns	_
Body to drain dic voltage	de forward	V_{DF}		1.0	—	V	$I_F = 10 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time		t _{rr}		350		ns	$I_{F} = 10 \text{ A}, V_{GS} = 0,$ $di_{F} / dt = 100 \text{ A} / \mu \text{s}$

Notes 1. Pulse Test

See characteristic curves of 2SK1157, 2SK1158



Package Dimensions



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